

### **Features**

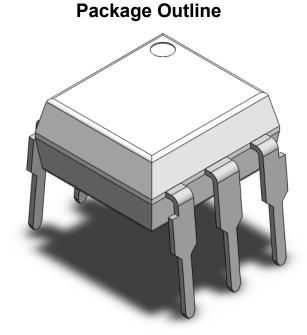
- High isolation 5000 VRMS
- Peak Breakdown Voltage
  - 600V CT3061, CT3062, CT3063
  - 800V CT3081, CT3082, CT3083
- Operating Temperature range 55 °C to 100 °C
- External Creepage ≥ 7.4mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 7.5mm (S/SL Type)
- Clearance Distance ≥ 8.0mm ( M/SLM Type)
- **RoHS and REACH Compliance**
- Halogen Free Compliance (Optional)
- MSL class 1
- **Regulatory Approvals** 
  - ✓ UL - UL1577 (E364000)
  - ✓ VDE - EN60747-5-5 (40039590)
  - CQC GB4943.1, 2022 (14001105802)  $\checkmark$
  - $\checkmark$ IEC62368 (FI/41119)

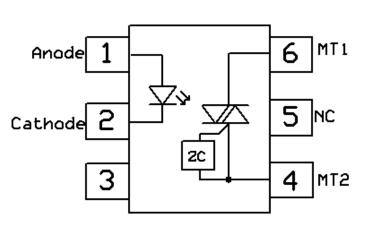
### Description

The CT3061, CT3062, CT3063, CT3081, CT3082 and CT3083 series consists of a Zero Cross Photo Triac optically coupled to an Infrared-emitting diode in a 6-lead DIP DMC-Isolator® package with different lead forming options.

### **Applications**

- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control





**Schematic** 

Note: Different lead forming options available. See package dimension.



### Absolute Maximum Ratings T<sub>A</sub> = 25°C, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters		Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 n	ninute, 40 ~ 60% R.H.)	5000	VRMS	
TOPR	Operating temperature		-55 ~ +100	°C	
Tstg	Storage temperature		-55 ~ +150	°C	
Tsol	Soldering temperature (F	or 10 seconds)	260	°C	
Emitter					
lF	Forward current		60	mA	
I <sub>F(TRANS)</sub>	Peak transient current (	≤1µs P.W,300pps)	1	A	
VR	Reverse voltage		6	V	
PD	Power dissipation		100		
ТJ	Junction temperature		125	°C	
Detector	•				
PD	Power dissipation		300	mW	
N/	Off-State Output	CT3061,CT3062,CT3063	600	V	
Vdrm	Terminal Voltage CT3081,CT3082,CT3083		800	V	
Ітѕм	Peak Repetitive Surge Current(100µs P.W, 120pps)		1	A	
ТJ	Junction temperature		125	°C	



### **Electrical Characteristics** *T<sub>A</sub>* = 25°*C*, unless otherwise specified

#### **Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Мах	Units	Notes
VF	Forward voltage	I <sub>F</sub> =10mA	-	-	1.5	V	
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 6V	-	-	5	μA	
CIN	Input Capacitance	f= 1MHz	-	45	-	pF	

#### **Detector Characteristics**

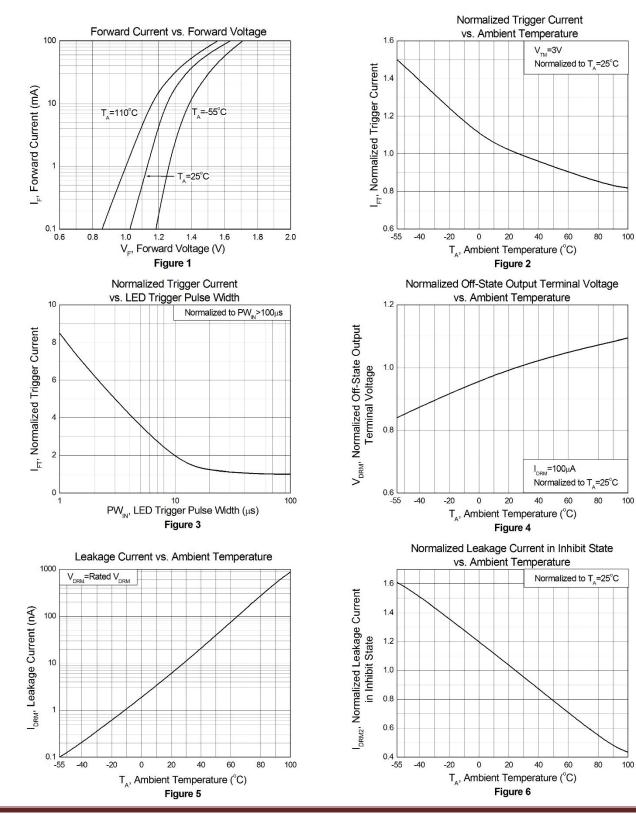
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I <sub>DRM1</sub>	Peak Blocking Current	I <sub>F</sub> = 0mA, V <sub>DRM</sub> = Rated V <sub>DRM</sub>	-	-	500	nA	
I <sub>DRM2</sub>	Inhibit Leakage Current	I <sub>F</sub> = Rated I <sub>FT,</sub> V <sub>DRM</sub> = Rated V <sub>DRM</sub>	-	-	500	μΑ	
VINH	Inhibit Voltage	I <sub>F</sub> = Rated I <sub>FT,</sub>	-	-	20	V	
Vтм	Peak On-State Voltage	I <sub>F</sub> = Rated I <sub>FT</sub> , I <sub>TM</sub> = 100mA	-	-	3	V	
dv/dt	Critical Rate of Rise off-State Voltage	VPEAK= Rated VDRM	1000	-	-	V/µs	

#### **Transfer Characteristics**

Symbol	Parameters		Test Conditions	Min	Тур	Max	Units	Notes
	Input	CT3061, CT3081	Terminal Valtage - 2V	-	-	15		
IFT	Trigger	CT3062, CT3082	Terminal Voltage = 3V	-	-	10	mA	
	Current	CT3063, CT3083		-	-	5		
	Holding Current		Terminal Voltage from "ON" to "OFF"		200		•	
Ін		unent	"ON" state I <sub>F</sub> =0mA	- 380 -		μA		
Rio	Isolation Resistance		V <sub>IO</sub> = 500V <sub>DC</sub>	1x10 <sup>11</sup>	-	-	Ω	
CIO	Isolation Capacitance		f= 1MHz	-	0.25	-	pF	



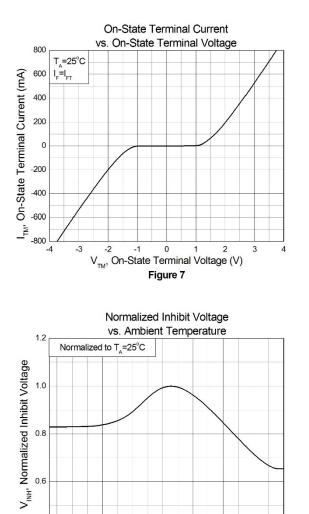
#### Typical Characteristic Curves T<sub>A</sub> = 25°C, unless otherwise specified

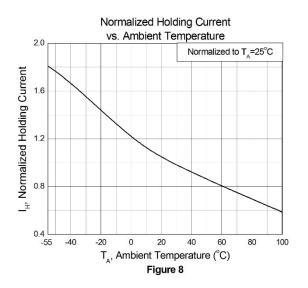


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#### Typical Characteristic Curves T<sub>A</sub> = 25°C, unless otherwise specified (Continued)





0.4

-40

0

-20

20

T<sub>A</sub>, Ambient Temperature (°C) **Figure 9** 

40

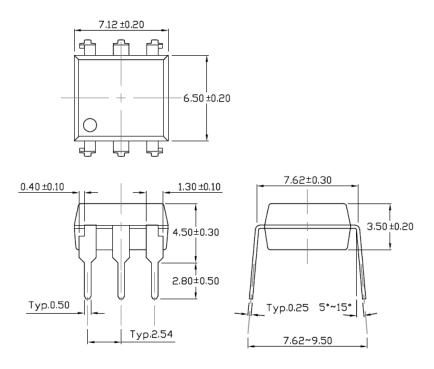
60

80

100



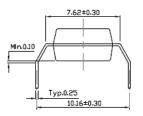
### Package Dimension Dimensions in mm unless otherwise stated



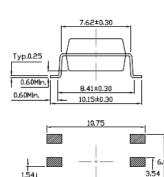
### Forming Option Dimensions in mm unless otherwise stated

1.00

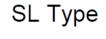
М Туре







7.55



8.41±0.30 10.15±0.30

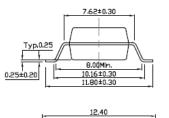
10.38

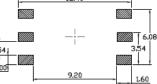
7.55

3,54

1.60

# SLM Type





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0.20Ma×

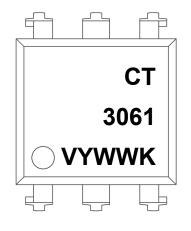
1.54

1.00

1.60



### **Marking Information**



#### Note:

- CT : Denotes "CT Micro"
- 3061 : Part Number
- X : CTR Rank Option (Blank, A or B)
- V : VDE Safety Mark Option (Blank or V)
- Y : One Digit Year Code
- WW : Two Digit Work Week
- K : Manufacturing Code

### **Ordering Information**

## CT306X(V)(Y)(Z)-G, CT308X(V)(Y)(Z)-G

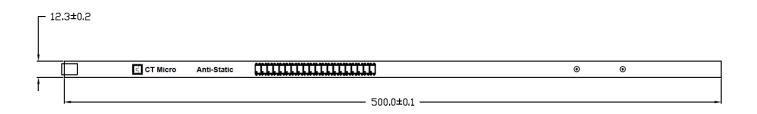
СТ	= Denotes "CT Micro"
306X	= Part No. (CT306X:1,2,3), (CT308X : 1,2,3)
V	= VDE Safety Mark Option (Blank or V)
Y	= Lead Form Option (Blank, S, SL, M or SLM)
Z	= Tape and Reel Option (Blank, T1 or T2)
G	= Material Option (G: Halogen Free, Blank: Non-Halogen Free)

Option	Description	Quantity
None	Standard 6 Pin Dip	50Units/Tube
М	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	1000 Units/Reel
SLM(T2)	Surface Mount (Gullwing) Lead Forming – With Option 2 Taping	1000 Units/Reel



#### **Carrier Specifications** Dimensions in mm unless otherwise stated

#### **Tube Option Standard DIP**

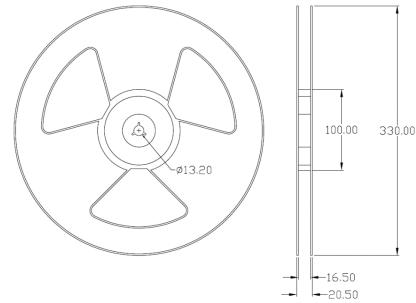


#### **Tube Option M Type**

	3.9±0.2					
	$\Box$	CT Micro	Anti-Static		۹	•
t						
	4			500,0±0,1		

### Reel Dimension Dimensions in mm unless otherwise stated

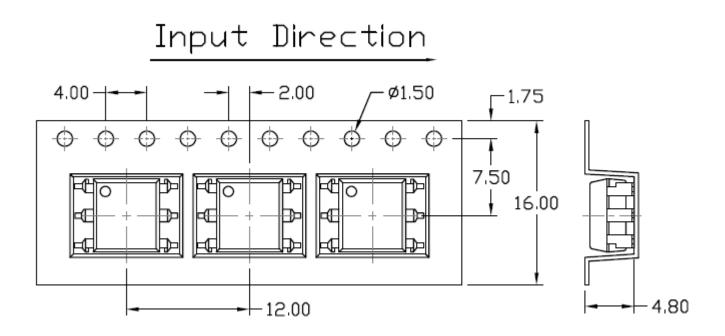
### Option S(T1/T2) & SL(T1/T2) & SLM(T1/T2)



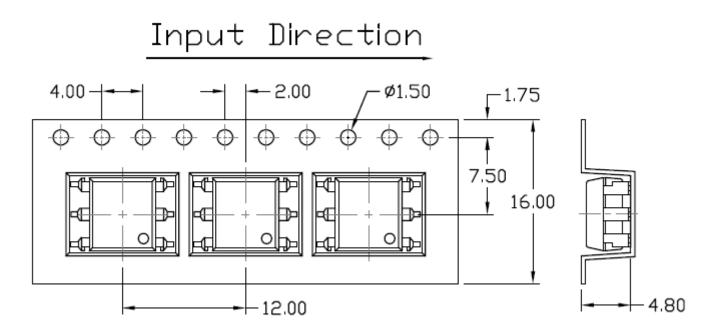


Carrier Tape Specifications Dimensions in mm unless otherwise stated

### Option S(T1) & SL(T1)

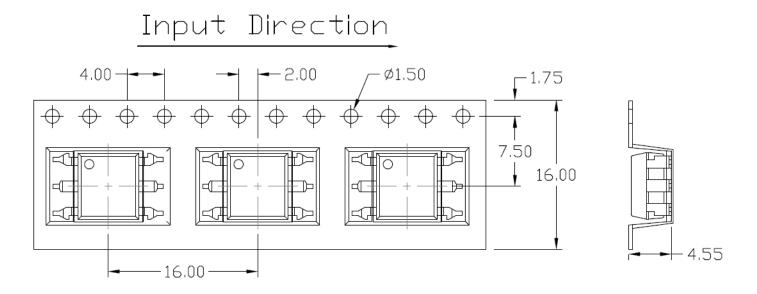


Option S(T2) & SL(T2)

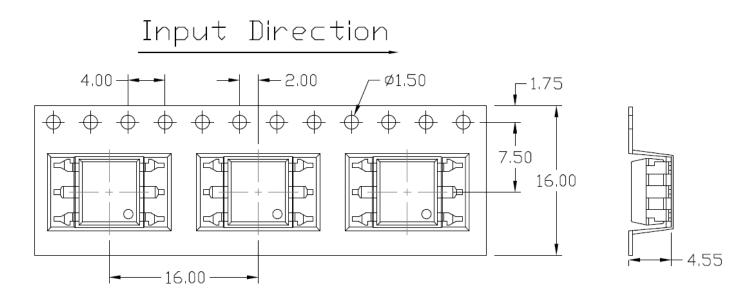




### **Option SLM(T1)**



### Option SLM(T2)





### Solderability Specification (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

### Wave soldering (follow the JEDEC standard JESD22-A111)

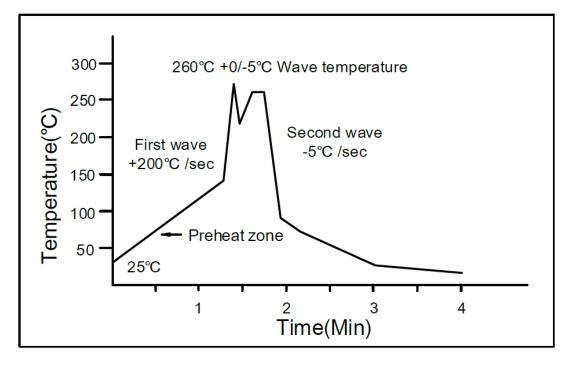
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



### Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

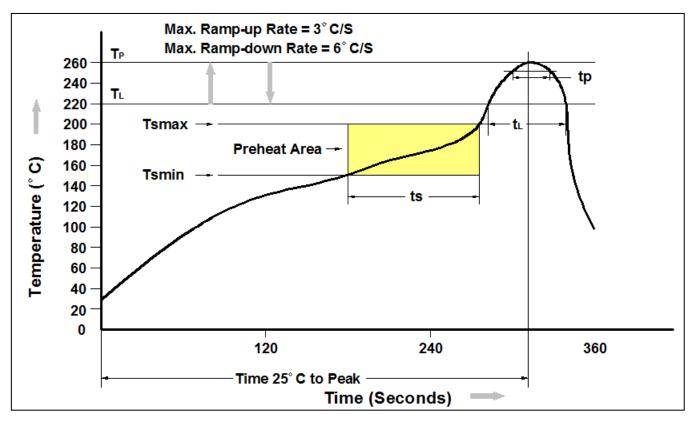
One time soldering is recommended.

Temperature: 350±10°C

Time: 5 sec max.



### **Reflow Profile (follow the JEDEC standard J-STD-020)**



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t₀) within 5°C of 260°C	30 seconds
Ramp-down Rate ( $T_P$ to $T_L$ )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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